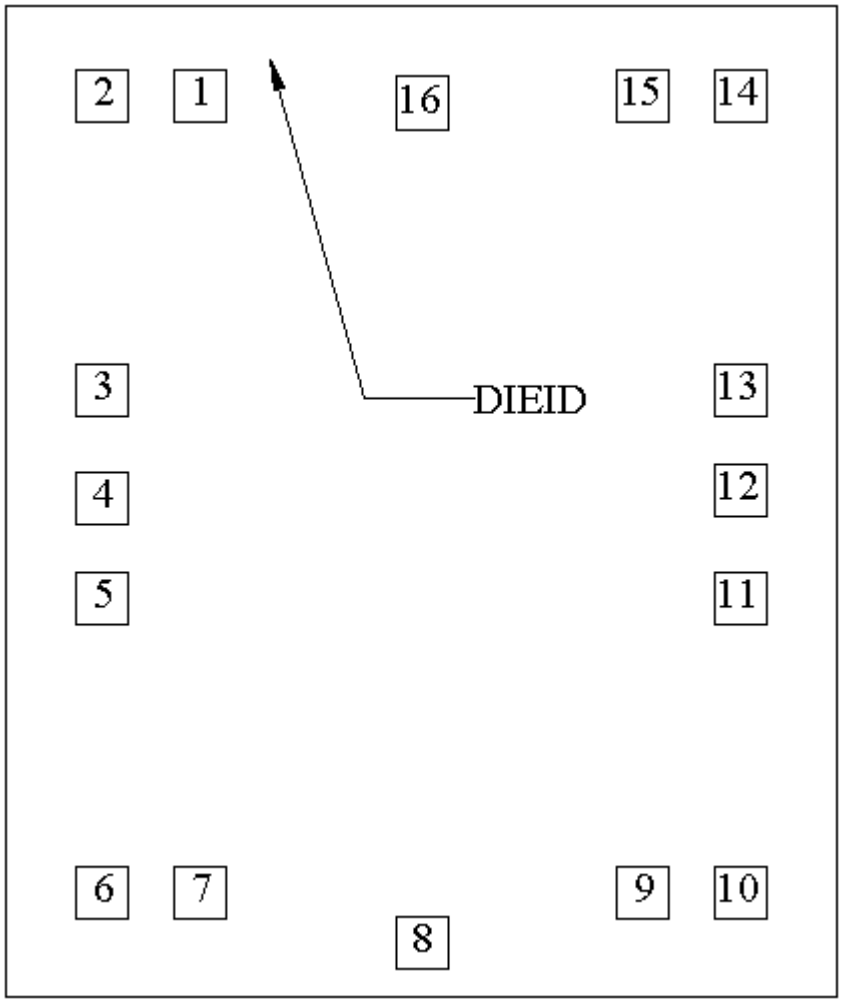
National Semiconductor
The Sight & Sound of Information

DPBU
Die Datasheet

DS26LS33 MD8 MW8
QUAD DIFFERENTIAL LINE RECEIVERS

May 17,2004

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		**General Die Information**	
Physical Die Identification	DS7633A	Bond Pad Opening Size (min)	91µm x 91µm
Die Step	A	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	NITRIDE
Wafer Diameter	100mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1448µm x 1727µm 57.0mils x 68.0mils	Back Side Connection	Floating
Thickness	330µm Nominal		
Min Pitch	172µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
INPUT A-	1	-386	706	91	x	91
INPUT A+	2	-556	706	91	x	91
OUTPUT A	3	-556	193	91	x	91
ENABLE	4	-556	5	91	x	91
OUTPUT C	5	-556	-170	91	x	91
INPUT C+	6	-556	-683	91	x	91
INPUT C-	7	-386	-683	91	x	91
GND	8	0	-770	91	x	91
INPUT D-	9	386	-683	91	x	91
INPUT D+	10	556	-683	91	x	91
OUTPUT D	11	556	-170	91	x	91
/ENABLE	12	556	18	91	x	91
OUTPUT B	13	556	193	91	x	91
INPUT B+	14	556	706	91	x	91
INPUT B-	15	386	706	91	x	91
VCC	16	0	693	91	x	91

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